

#### **Features**

- · Excellent Stability and Uniformity
- · Split Gate Trench Mosfet Technology
- Lower R<sub>DS(ON)</sub>
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free ."Green" Device (Note 1)
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)
- · Moisture Sensitivity Level 1

# N-CHANNEL MOSFET

# **Maximum Ratings**

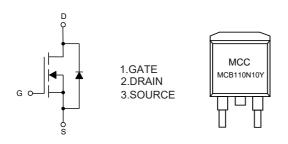
- Operating Junction Temperature Range: -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance: 0.48°C/W Junction to Case

Parameter	Symbol	Rating	Unit		
Drain -Source Voltage		V <sub>DS</sub>	100	V	
Gate -Source Volltage		V <sub>GS</sub>	±20	V	
Drain Current-Continuous	T <sub>C</sub> =25°C		110	Α	
	T <sub>C</sub> =100°C	- I <sub>D</sub>	70		
Drain Current-Pulse(Note2)		I <sub>DM</sub>	440	Α	
Power Dissipation		P <sub>D</sub>	260	W	
Single Pulsed Avalanche Energy <sup>(Note3)</sup>		E <sub>AS</sub>	400	mJ	

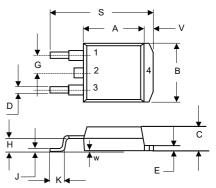
#### Notes:

- 1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 2. Pulse Width Limited by Maximum Junction Temperature.
- 3. EAS Condition: $T_J=25^{\circ}C$ ,  $V_{DD}=50V$ ,Rg= $25\Omega$ ,L=2mH,I<sub>AS</sub>=31A.

# **Internal Structure and Marking Code**



# D<sup>2</sup>-PAK



DIMENSIONS					
DIM INCHES MIN MAX		MM		NOTE	
		MAX	MIN	MAX	NOTE
Α	0.331	0.370	8.40	9.40	
В	0.378	0.417	9.60	10.60	
С	0.165	0.189	4.20	4.80	
D	0.027	0.037	0.68	0.94	
Е	0.045	0.055	1.14	1.40	
G	0.10		2.54		TYP.
Н	0.096	0.134	2.43	3.40	
J	0.011	0.025	0.28	0.64	
K	0.071	0.131	1.80	3.32	
S	0.575	0.625	14.60	15.87	
V	0.042	0.058	1.07	1.47	
W	0.000	0.010	0.00	0.25	

#### **Suggested Solder Pad Layout**

10.26



# Electrical Characteristics @ 25°C (Unless Otherwise Noted)

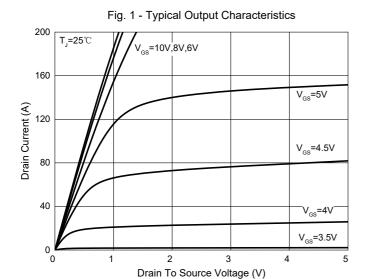
Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit	
Static Characteristics	<u>.                                      </u>				<u> </u>		
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS}$ =0V, $I_{D}$ =250 $\mu$ A	100			V	
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V			±100	nA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =100V, V <sub>GS</sub> =0V,T <sub>J</sub> =25°C			1	uA	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS}=V_{GS}$ , $I_{D}=250\mu A$	2.0	2.8	4.0	V	
Drain-Source On-Resistance (Note4)	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =20A		4.5	5	mΩ	
Gate resistance	$R_{G}$	V <sub>GS</sub> =0V,f=1MHz		0.9		Ω	
Body Diode Voltage	V <sub>SD</sub>	I <sub>SD</sub> =20A, V <sub>GS</sub> =0V			1.3	V	
Dynamic Characteristics(Note 5)	)						
Input Capacitance	C <sub>iss</sub>			4600		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS}$ =50V, $V_{GS}$ =0V,f=1MHz		1250			
Reverse Transfer Capacitance	C <sub>rss</sub>			43			
Total Gate Charge	Qg			66			
Gate-Source Charge	$Q_{gs}$	$V_{DS}$ =50V, $V_{GS}$ =10V, $I_{D}$ =20A		23		<b>"</b> C	
Gate-Drain Charge	$Q_{gd}$			6.6		nC	
Reverse Recovery Charge	Q <sub>rr</sub>	L _00A di/dt_400A/		93			
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> =20A,di/dt=100A/μs		63			
Turn-On Delay Time	t <sub>d(on)</sub>			17.6			
Turn-On Rise Time	t <sub>r</sub>	V <sub>DS</sub> =50V,I <sub>D</sub> =20A,		30.2		ns	
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GS}$ =10 $V$ , $R_{G}$ =2.2 $\Omega$		33.6			
Turn-Off Fall Time	t <sub>f</sub>			39.6			

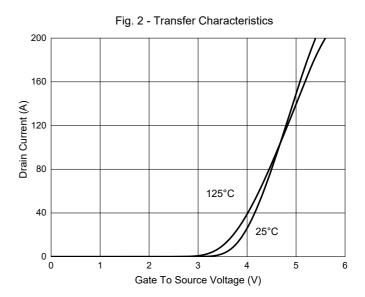
Note 4. Pulse Test : Pulse Width≤300µs, Duty Cycle ≤2%.

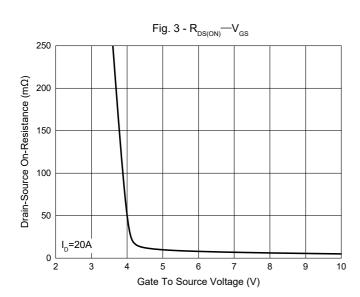
<sup>5.</sup> Guaranteed by Design, Not Subject to Production Testing.

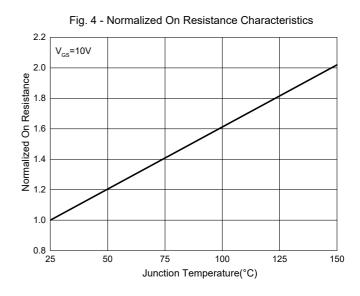


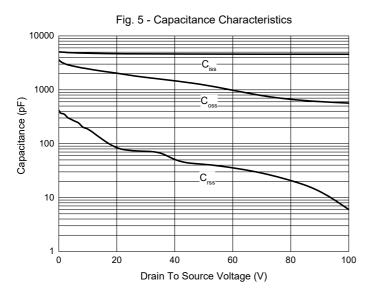
## **Curve Characteristics**

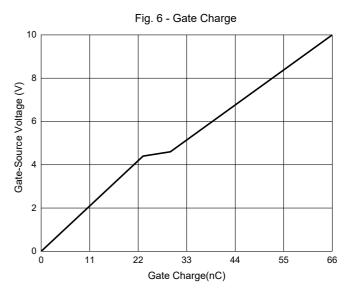














### **Curve Characteristics**

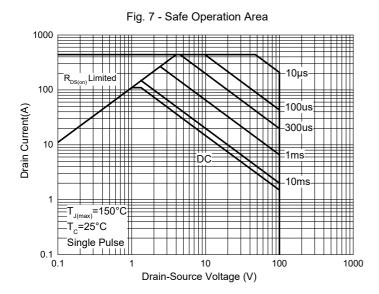
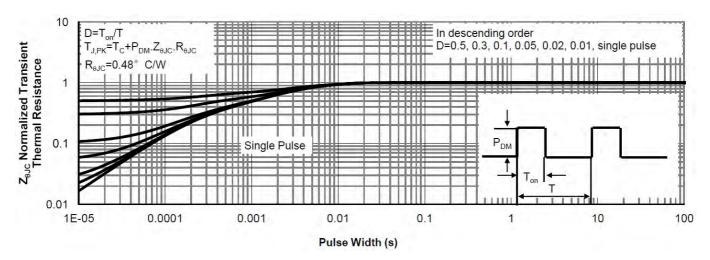


Fig.8 - Normalized Maximum Transient thermal impedance





### **Ordering Information**

Device	Packing	
Part Number-TP	Tape&Reel: 800pcs/Reel	

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